

80C49-7/80C39-7 CHMOS SINGLE-COMPONENT 8-BIT MICROCOMPUTER

- 80C49-7 Low Power Mask Programmable ROM
- 80C39-7 Low Power, CPU only
- Pin-to-pin Compatible with Intel's 8049AH/8039AHL
- 1.36 μsec Instruction Cycle. All Instructions
 1 or 2 Cycles
- Ability to Maintain Operation during AC Power Line Interruptions
- Exit Idle Mode with an External or Internal Interrupt Signal

- **■** Battery Operation
- 3 Power Consumption Selections
 - -Normal Operation: 12 mA @ 11 MHz @ 5V
 - —Idle Mode: 5 mA @ 11 MHz @ 5V
 - -Power Down: 2 μA @ 2.0V
- 11 MHz, TTL Compatible Operation:

VCC = 5V ± 10%

CMOS Compatible Operation;

VCC = 5V ± 20%

Intel's 80C49-7/80C39-7 are low power, CHMOS versions of the popular MCS²-48 HMOS family members. CHMOS is a technology built on HMOS II and features high resistivity P substrate, diffused N well, and scaled N and P channel devices. The 80C49-7/80C39-7 have been designed to provide low power consumption and high performance.

The 80C49-7 contains a 2K x 8 program memory, a 128 x 8 x 8 RAM data memory, 27 I/O lines, and an 8-bit timer/counter in addition to an on-board oscillator and clock circuits. For systems that require extra capability, the 80C49-7 can be expanded using CMOS external memories and MCS*-80 and MCS*-85 peripherals. The 80C39-7 is the equivalent of the 80C49-7 without program memory on-board.

The CHMOS design of the 80C49-7 opens new application areas that require battery operation, low power standby, wide voltage range, and the ability to maintain operation during AC power line interruptions. These applications include portable and hand-held instruments, telecommunications, consumer, and automotive.

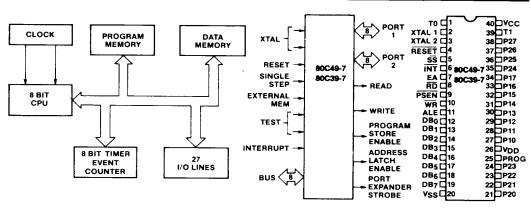


Figure 1. Block Diagram

Figure 2. Logic Symbol

Figure 3.
Pin Configuration



Table 1. Pin Description

Symbol	Pin No.	Function
V _{SS}	20	Circuit GND potential
V_{DD}	26	Low Power standby pin
VCC	40	Main power supply; +5V during operation.
PROG	25	Output strobe for 82C43 I/O expander.
P10-P17 Port 1	27-34	8-bit quasi-bidirectional port.
P20-P23	21-24	8-bit quasi-bidirectional port.
P24-P27 Port 2	35-38	P20-P23 contain the four high order program counter bits during an external program memory fetch and serve as a 4-bit I/O expander bus for 8243.
DB0-DB7 BUS	12-19	True bidirectional port which can be written or read synchronously using the RD, WR strobes. The port can also be statically latched.
		Contains the 8 low order program counter bits during an external program memory fetch, and receives the addressed instruction under the control of PSEN. Also contains the address and data during an external RAM data store instruction, under control of ALE, RD, and WR.
то -	1	Input pin testable using the conditional transfer instructions JT0 and JNTo. T0 can be designated as a clock output using ENT0 CLK instruction.
T1	39	Input pin testable using the JT1, and JNT1 instructions.

Symbol	Pin No.	Function	
		Can be designated the timer/counter input using the STRT CNT instruction.	
INT	6	Interrupt input. Initiates an interrupt if interrupt is enabled. Interrupt is disabled after a reset. Also testable with conditional jump instruction. (Active low) Interrupt must remain low for at least 3 machine cycles for proper operation.	
RD	8	Output strobe activated during a BUS read. Can be used to enable data onto toe bus from an external device.	
	-	Used as a read strobe to external data memory. (Active low)	
RESET	4	Input which is used to initialize the processor. (Active low) (Non TTL VIH)	
WR	10	Output strobe during a bus write. (Active low)	
		Used as write strobe to external data memory.	
ALE	11	Address latch enable. This signal occurs once during each cycle and is useful as a clock output.	
		The negative edge of ALE strobes address into external data and program memory.	
PSEN	9	Program store enable. This output occurs only during a fetch to external program memory. (Active low)	
SS	5	Single step input can be used in conjunction with	



Table 1. Pin Description (Continued)

Symbol	Pin No.	Function
SS (Con't)		ALE to "single step" the processor through each instruction (Active low)
EA	7	External access input which forces all program memory fetches to reference external memory. Useful for emulation and debug, and essential for testing

Symbol	Pin No.	Function
		and program verification. (Active high)
XTAL1	2	One side of crystal input for internal oscillator. Also input for external source. (Non TTL V _{IH})
XTAL2	3	Other side of crystal input.

IDLE MODE DESCRIPTION

The 80C49-7, when placed into Idle mode, keeps the oscillator, the internal timer and the external interrupt and counter pins functioning and maintains the internal register and RAM status.

To place the 80C49-7 in Idle mode, a command instruction (op code 01H) is executed. To terminate Idle mode, a reset must be performed or interrupts must be enabled and an interrupt signal generated. There are two interrupt sources that can restore normal operation. One is an external signal applied to the interrupt pin. The other is from the overflow of the timer/counter. When either interrupt is invoked, the CPU is taken out of Idle mode and vectors to the interrupt's service routine address. Along with the Idle mode, the standard MCS*-48 power-down mode is still maintained.



Table 2. Instruction Set

Accumulator			
Mnemonic	Description	Bytes	Cycles
ADD A, R	Add register to A	1	1
ADD A, @R	Add data memory to A	1	1
ADD A, # data	Add immediate to A	2	2
ADDC A, R	Add register with carry	1	1
ADDC A, @R	Add data memory with carry	1	1
ADDC A, # data	Add immediate with carry	2	2
ANL A, R	And register to A	1	1
ANL A, @R	And data memory to A	1	1
ANL A, # data	And immediate to A	2	2
ORL A, R	Or register to A	1	1
ORL A @R	Or data memory to A	1	1
ORL A, # data	Or immediate to A	2	2
XRL A, R	Exclusive or register to A	1	1
XRL A, @R	Exclusive or data memory to A	1	1
XRL, A, # data	Exclusive or immediate to A	2	2
INC A	Increment A	1	1
DEC A	Decrement A	1	1
CLR A	Clear A	1	1
CPL A	Complement A	1	1
DA A	Decimal adjust A	1	1
SWAP A	Swap nibbles of A	1	1
RL A	Rotate A left	1	1
RLC A	Rotate A left through carry	1	1
RR A	Rotate A right	1	1
RRC A	Rotate A right through carry	1	1

Input/Output			
Mnemonic	Description	Bytes	Cycles
IN A, P	Input port to A	1	2
OUTL P, A	Output A to port	1	2
ANL P, # data	And immediate to port	2	2
ORL P, # data	Or immediate to port	2	2
INS A, BUS	Input BUS to A	1	2
OUTL BUS, A	Output A to BUS	1	2
ANL BUS, # data	And immediate to BUS	2	2
ORL BUS, # data	Or immediate to BUS	2	2
MOVD A, P	Input expander port to A	1	2
MOVD P, A	Output A to expander port	1	2
ANLD P, A	And A to expander port	1	2
ORLD P, A	Or A to expander port	1	2

Registers			
Mnemonic	Description	Bytes	Cycles
INC R	Increment register	1	1
INC @R	Increment data memory	1	1
DECR	Decrement register	1	1

Branch	-		
Mnemonic	Description	Bytes	Cycles
JMP addr	Jump unconditional	2	2
JMPP @A	Jump indirect	1	2
DJNZ R, addr	Decrement register and skip	2	2
JC addr	Jump on carry = 1	2	2
JNC addr	Jump on carry = 0	2	2
JZ addr	Jump on A zero	2	2
JNZ addr	Jump on A not zero	2	2
JT0 addr	Jump on T0 = 1	2	2
JNT0 addr	Jump on T0 = 0	2	2
JT1 addr	Jump on T1 = 1	2	2
JNT1 addr	Jump on T1 = 0	2	2
JF0 addr	Jump on F0 = 1	2	2
JF1 addr	Jump on F1 = 1	2	2
JTF addr	Jump on timer flag	2	2
JNI addr	Jump on INT = 0	2	2
JBb addr	Jump on accumulator bit	2	2

Subroutine			
Mnemonic	Description	Bytes	Cycles
CALL addr	Jump to subroutine	2	2
RET	Return	1	2
RETR	Return and restore status	1	2

Flags			
Mnemonic	Description	Bytes	Cycles
CLR C	Clear carry	1	1
CPL C	Complement carry	1	1
CLR F0	Clear flag 0	1	1
CPL F0	Complement flag 0	1	1
CLR F1	Clear flag 1	1	1
CPL F1	Complement flag 1	1	1
Ì			

210936

15-37



Table 2. Instruction Set (Continued)

Mnemonic	Description	Bytes	Cycle
MOV A, R	Move register to A	1	1
MOV A, @R	Move data memory to A	1	1
MOV A, # data	Move immediate to A	2	2
MOV R, A	Move A to register	1	1
MOV @R, A	Move A to data memory	1	1
MOV R, # data	Move immediate to register	2	2
MOV @R, # dat	a Move immediate to data memory	2	2
MOV A, PSW	Move PSW to A	1	1
MOV PSW, A	Move A to PSW	1	1
XCH A, R	Exchange A and register	1	1
XCH A, @R	Exchange A and data memory	1	1
XCHD A, @R	Exchange nibble of A and register	1	.1
MOVX A, @R	Move external data memory to A	1	2
MOVX @R, A	Move A to external data memory	1	2
MOVP A, @A	Move to A from current page	1	2
MOVP3 A, @A	Move to A from page 3	1	2

Timer/Counter			
Mnemonic	Description	Bytes	Cycles
MOV A, T	Read timer/counter	1	1
MOV T, A	Load timer/counter	1	1
STRTT	Start timer	1	1
STRT CNT	Start counter	1	1
STOP TONT	Stop timer/counter	1	1
EN TCNTI	Enable timer/counter interrupt	1	1
DIS TONTI	Disable timer/counter interrupt	1	1

Control			
Mnemonic	Description	Bytes	Cycles
ENI	Enable external interrupt	1	1
DIS I	Disable external interrupt	1	1
SEL RB0	Select register bank 0	1	1
SEL RB1	Select register bank 1	1	1
SEL MB0	Select memory bank 0	1	1
SEL MB1	Select memory bank 1	1	1
ENTO CLK	Enable clock output on T0	1	1

Mnemonic	Description	Bytes	Cycles
NOP	No operation	1	1
IDL	Select Idle Operation	1	1

ABSOLUTE MAXIMUM RATINGS*

Ambient Temperature Under Bias 0°C to 70°C
Storage Temperature65°C to +150°C
Voltage On Any Pin With Respect
to Ground 0.5V to V _{CC} +1V
Maximum Voltage On Any Pin
With Respect to Ground
Power Dissipation 1.0 Watt

*NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

15-38

IARACTERISTICS: (T_A = 0°C to 70°C; $V_{CC} = V_{DD} = 5V \pm 20\%$; $|V_{CC} - V_{DD}| \le 1.5V$; $V_{SS} = 0V$

Γ	V33 V1)	Limits				
À	Parameter	Min	Тур	Max	Unit	Test Conditions
1	Input Low Voltage (All Except X1, RESET)	5		.18 V _{CC}	٧	
7	Input Low Voltage X1, RESET	-5		.13 V _{CC}	V	
1	Input High Voltage (All Except XTAL1, RESET)	0.2 V _{CC} + 1.2		VCC	٧	
	Input High Voltage (X1, RESET)	.7 V _{CC}		Vcc	٧	
. 1	Output Low Voltage (BUS)			.6	٧	I _{OL} = 2.0 mA
_1	Output Low Voltage (RD, WR, PSEN, ALE)			.6	V	I _{OL} = 1.8 mA
12	Output Low Voltage (PROG)			.6	٧	I _{OL} = 1.0 mA
)L3	Output Low Voltage (All Other Outputs)			.6	٧	I _{OL} = 1.6 mA
ЭН	Output High Voltage (BUS)	.75 VCC			V	$i_{OH} = -400 \mu A$
DH1	Output High Voltage (RD, WR, PSEN, ALE)	.75 V _{CC}			V	I _{OH} = -100 μA
OH2	Output High Voltage (All Other Outputs)	2.4 3.0			V	$I_{OH} = -40 \mu A$ $I_{OH} = -20 \mu A$
L1	Input Leakage Current (T1, INT, EA)]	±5	μΑ	V _{SS} ≤ V _{IN} ≤ V _{CC}
LI1	Input Leakage Current (P10-P17, P20-P27, SS)			-500	μΑ	V _{SS} ≤ V _{IN} ≤ V _{CC}
l _{LO}	Output Leakage Current (BUS, TO) (High Impedance State)			±5	μΑ	V _{SS} ≤ V _{IN} ≤ V _{CC}
ILB	Input Leakage Current (RESET)	- 10		-300	μΑ	V _{SS} ≤ V _{IN} ≤ V _{IH1}
IPD	Power Down Standby Current		<u> </u>	2	μA	V _{DD} = 2.0V RESET ≤ V _{IL}

Icc Active Current (mA)

<u></u>	ICC HOME CALLED A COLUMN						
V _C C	4V	5V	6V				
1 MHz	2.5	3.3	4.0				
6 MHz	5	6.8	8.5				
11 MHz	9	12	15				

ICC Idle Current (mA)

· Vcc	4V	5V	6V
1 MHz	1.7	2.0	2.2
6 MHz	2	3	4
11 MHz	3.5	4.8	6

Absolute Maximum Unloaded Current

ICC Test Conditions:

ICC Active

All outputs disconnected

T1, INT, SS, T0 connected to HIGH (V_{IH}) EA, RST connected to LOW (V_{IL})

XTAL1 External Drive

Rise Time = 10 ns, Fall Time = 10 ns

XTAL2 No connection $V_{IH} = V_{CC} - 0.5V$ $V_{IL} = V_{SS} + 0.5V$

ICC Idle

All outputs disconnected

XTAL1 External Drive

Rise Time = 10 ns, Fall Time = 10 ns

XTAL2 No connection

 $V_{IH} = V_{CC} - 0.5V$ $V_{IL} = V_{SS} + 0.5V$

15-39



A.C. CHARACTERISTICS: $(T_A = 0^{\circ} \text{ C to } 70^{\circ} \text{ C}; V_{CC} = V_{DD} = 5 \text{ V} \pm 20\%; |V_{CC} - V_{DD}| \leqslant 1.5 \text{ V}; V_{SS} = 0 \text{ V})$

Symbol		f (t) (Note 3)	11	MHz	Unit	Conditions (Note 1)
			Min	Max		
t	Clock Period	1/xtal freq	90.9	1000	ns	(Note 3)
tLL	ALE Pulse Width	3.5t-170	150		ns	
†AL	Addr Setup to ALE	2t-110	70		ns	(Note 2)
tLA	Addr Hold from ALE	t-40	50		ns	
tCC1	Control Pulse Width (RD, WR)	7.5t-200	480		ns	
tCC2	Control Pulse Width (PSEN)	6t-200	350		ns	
^t DW	Data Setup before WR	6.5t-200	390		ns	
tWD	Data Hold after WR	t-50	40		ns	
^t DR	Data Hold (RD, PSEN)	1.5t-30	0	110	ns	
t _{RD1}	RD to Data in	6t-170		350	ns	
^t RD2	PSEN to Data in	4.5t-170	1	190	ns	
t _{AW}	Addr Setup to WR	5t-150	300	 	ns	
^t AD1	Addr Setup to Data (RD)	10.5t-220		730	ns	
t _{AD2}	Addr Setup to Data (PSEN)	7.5t-220	1	460	ns	
^t AFC1	Addr Float to RD, WR	2t-40	140		ns	(Note 2)
^t AFC2	Addr Float to PSEN	.5t-40	10		ns	(Note 2)
tLAFC1	ALE to Control (RD, WR)	3t-75	200		ns	,
tLAFC2	ALE to Control (PSEN)	1.5t-75	60		ns	
t _{CA1}	Control to ALE (RD, WR, PROG)	t-65	25		ns	
tCA2	Control to ALE (PSEN)	4t - 70	290		ns	
tCP	Port Control Setup to PROG	1.5t-80	50		ns	
t _{PC}	Port Control Hold to PROG	4t-260	100		ns	
tPR	PROG to P2 Input Valid	8.5t-120		650	ns	
tpF	Input Data Hold from PROG	1.5t	0	140	ns	
^t DP	Output Data Setup	6t-290	250		ns	
^t PD	Output Data Hold	1.5t-90	40		ns	
tpp	PROG Pulse Width	10.5t-250	700		ns	
tpL	Port 2 I/O Setup to ALE	4t-200	160		ns	
tLP	Port 2 I/O Hold to ALE	1.5t-120	15		ns	
tpv	Port Output from ALE	4.5t+100		510	ns	
OPRR	T0 Rep Rate	3t	270		ns	
tCY	Cycle Time	15t	1.36	15.0	μS	

Notes:

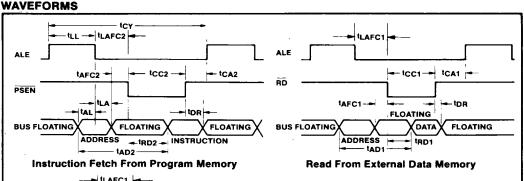
15-40

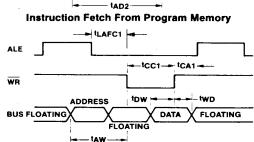
Control Outputs CL = 80pF BUS Outputs CL = 150pF

^{2.} BUS High Impedance Load 20pF

^{3.} f(t) assumes 50% duty cycle on X1, X2. Max clock period is for a 1 MHz crystal input.







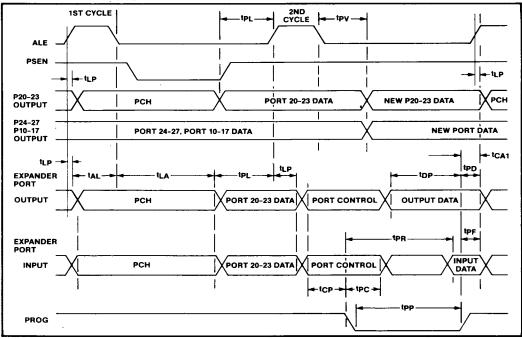
Write To External Data Memory

0.45V

A.C. testing inputs are driven at 2.4V for a logic "1" and 0.45V for a logic "0." Output timing measurements are made at 2.0V for a logic "1" and 0.8V for a logic "0."

Input And Output For A.C. Tests

PORT 1/PORT 2 TIMING



15-41



